

WHAT IS CLAIMED IS

1. A semiconductor device comprising:

a pair of impurity diffused regions formed in a silicon substrate, spaced from each other; and

a gate electrode formed above the silicon substrate between the pair of impurity diffused regions intervening a gate insulation film therebetween, the gate electrode being formed of a first polycrystalline silicon film formed on the gate insulation film, a second polycrystalline silicon film formed on the first polycrystalline silicon film and having crystal grain boundaries which are discontinuous to the first polycrystalline silicon film, and a metal nitride film formed on the second polycrystalline silicon film.

2. A semiconductor device comprising:

a pair of impurity diffused regions formed in a silicon substrate, spaced from each other; and

a gate electrode formed above the silicon substrate between the pair of impurity diffused regions intervening a gate insulation film therebetween, the gate electrode being formed of a first polycrystalline silicon film formed on the gate insulation film, a second polycrystalline silicon film formed on the first polycrystalline silicon film and having crystal grain boundaries which are discontinuous to the first polycrystalline silicon film, a metal nitride film formed on the second polycrystalline

silicon film, and a metal film form on the metal nitride film.

3. A semiconductor device according to claim 1, wherein

a native oxide film is formed between the first polycrystalline silicon film and the second polycrystalline silicon film.

4. A semiconductor device according to claim 2, wherein

a native oxide film is formed between the first polycrystalline silicon film and the second polycrystalline silicon film.

5. A semiconductor device according to claim 1, wherein

the first polycrystalline silicon film is doped with boron.

6. A semiconductor device according to claim 2, wherein

the first polycrystalline silicon film is doped with boron.

7. A semiconductor device according to claim 1, wherein

the first polycrystalline silicon film and the second polycrystalline silicon film are doped with boron, a boron concentration in the first polycrystalline silicon film near an interface between the first polycrystalline silicon

11. A method for fabricating a semiconductor device comprising the steps of:

forming a gate insulation film on a silicon substrate;
forming a first silicon film doped with boron on the
gate insulation film;

```
forming a second silicon film on the first silicon
film;
```

forming a metal nitride film on the second silicon film;

forming a metal film on the metal nitride film; and
patterning a layered structure of the first silicon
film, the second silicon film, the metal nitride film and
the metal film to form a gate electrode of the layered
structure.

12. A method for fabricating a semiconductor device according to claim 11, wherein

the step of forming the first silicon film includes the step of forming a polycrystalline silicon film on the gate insulation film and the step of doping boron in the polycrystalline silicon film.

13. A method for fabricating a semiconductor device according to claim 12, further comprising between the step of forming the polycrystalline silicon film and the step of doping boron,

the step of amorphizing the surface of the polycrystalline silicon film.

